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I, Romi Omar Mayder, declare as follows:

I am a defendant in this case and have personal knowledge of the all facts set forth in this declaration and, if called upon to testify in this Court as to those facts, my testimony would be as stated herein.

#### Personal History

- I began employment with Hewlett Packard on June 15, 1998, after being hired away from 2. Schlumberger. In 2000 Agilent spun off from Hewlett Packard and I continued employment with Agilent. On June 1, 2006 Verigy spun off from Agilent and I continued employment with Verigy until September 21, 2006, at which time I terminated employment.
- While working for Agilent, I reported to Bob Pochowski, who was general manager of 3. Agilent's Memory Test Division. In September of 2005 Mr. Pochowski left Agilent to pursue other career opportunities.

#### Semiconductor Wafer Testing Overview

- Testing During Wafer Sort: Flash memory wafers are tested by inserting them into a memory 4. tester. Memory testers, such as those manufactured by Verigy and Teradyne, are large electromechanical test equipment that send electrical signals to the memory device (called the Device Under Test or DUT). The electrical signals write a pattern of ones and zeros into each memory cell and then read each back to ensure that the pattern received was identical to the pattern originally written. If the pattern is not identical, the test fails and the die marked "bad."
- At the highest level, memory test systems have three components: a memory tester; a probe 5. card; and the DUT (here, a wafer). The memory tester consists of a system bay, test head, and wafer prober. A pattern of signals is programmed at the system bay, and the signals are electrically sent through the test head. The test head contains processors for executing test patterns, local memory for

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storing those test patterns, and switches so that individual signals can be routed from one input to multiple or different outputs. The test head interfaces with a wafer by connecting to a probe card. The probe card transfers the electrical signals to the wafer under test. The wafer prober holds the wafer that will be tested. When the probe card properly aligns with, and contacts the wafer, and the programmed electrical signals begin to test the DUT, it is called a "touchdown." The fewer number of touchdowns necessary to test an entire wafer, the lower the cost of testing the DUTs. Similarly, the greater the number of DUTs that can be tested with a single touchdown the lower the cost of test ("COT").

- 6. While there are many kinds of memory, of interest here are NAND flash memory and NOR flash memory. These two types of flash memory have some distinct performance and application differences.
- For NOR flash memory this write/read pattern testing must be fast and virtually flawless to 7. ensure proper working of the DUT. NAND flash memory is less demanding regarding speed of the tester and the accuracy of the test. NAND flash is ideal for high capacity, low reliability, data storage (such as needed in digital cameras), while NOR flash is best used for low capacity, high reliability (such as cell phone information). NOR flash allows for random access to the data. In other words, the data contained at any single memory address can be individually retrieved via a parallel interface. NAND flash does not allow for random access to data because information is retrieved in large blocks (such as 1024 to 2048 bytes) via a serial interface.
- More sophisticated testing resources are required to test NOR flash (than NAND flash memory) because of (1) the extremely fast read cycle; and (2) the high number of pins used to individually address each memory storage cell. The read cycle time of less than 8 nanoseconds for NOR memory forces testing equipment to operate within extremely short time cycles. For example,

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Since each NOR memory cell is individually readable the device must have 32 or 64 pins dedicated to addressing. In contrast, NAND memories require only 8 pins to read the memory cells. This four or eight fold increase in the number of address pins requires tester equipment with four to eight times the number of channels to test the device.

#### Gaining Efficiency In Wafer Sort Testing

- 9. As mentioned above, the greater the number of DUTs tested with a single touchdown, the lower the COT. Since memory testers are large expensive machines their tester channels are sometime referred to as a "resource." In order to gain more efficiency from this "resource" circuits are put on the probe card so that the tester resource is offloaded, or "shared," so that a greater number of DUTs can be tested simultaneously. This mounting of circuits on probe cards is sometimes referred to as probe card resource sharing.
- 10. In its simplest form a probe card resource sharing circuit consists of a circuit that simply fans out the test signal from the memory tester to two or more DUTs. This form of resource sharing is called fan out, because the signals "fan-out" to two or more DUTs simultaneously.
- In a more sophisticated example of probe card resource sharing, the probe card includes a 11. semiconductor switch which not only fans-out, but also selectively transmits the test signals from the memory tester to the wafer. This is commonly referred to as multiplexing. The switches can be implemented with electrical relays or field effect transistors ("FETS"). A multiplex circuit allows tester resources to be fanned out to multiple DUTs, while maintaining the uniqueness of each DUT, and the ability to disconnect failing DUTs.
- 12. Multiplex probe card resource sharing circuits have been and are currently being practiced by

Document 55

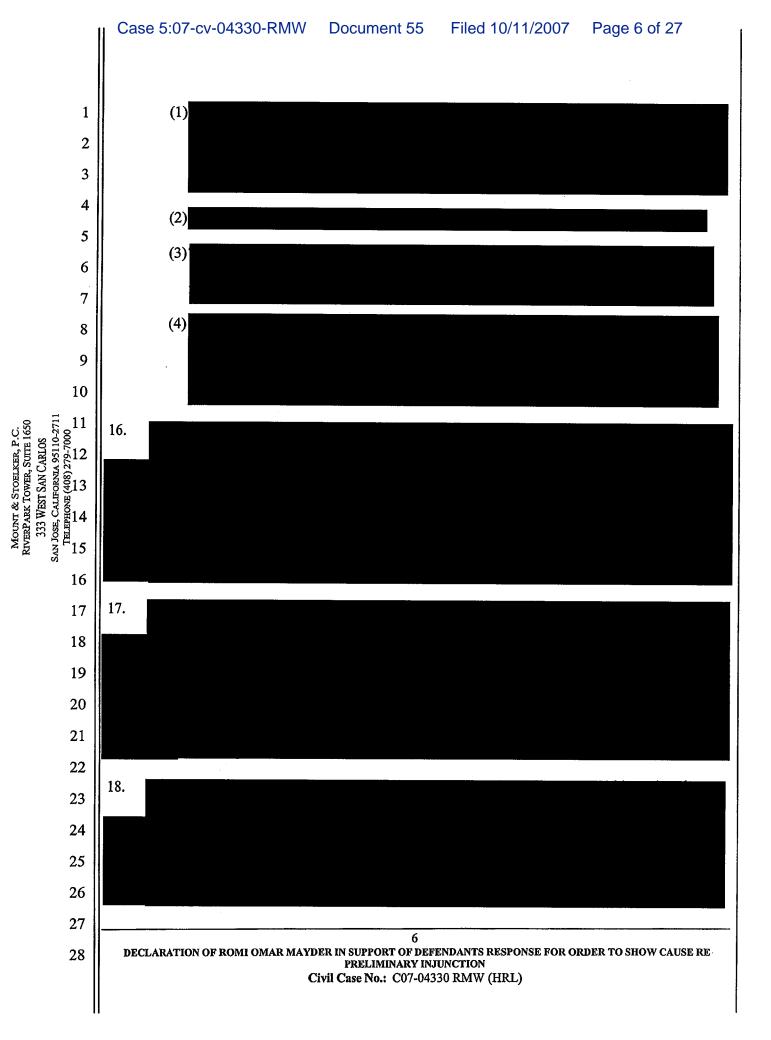
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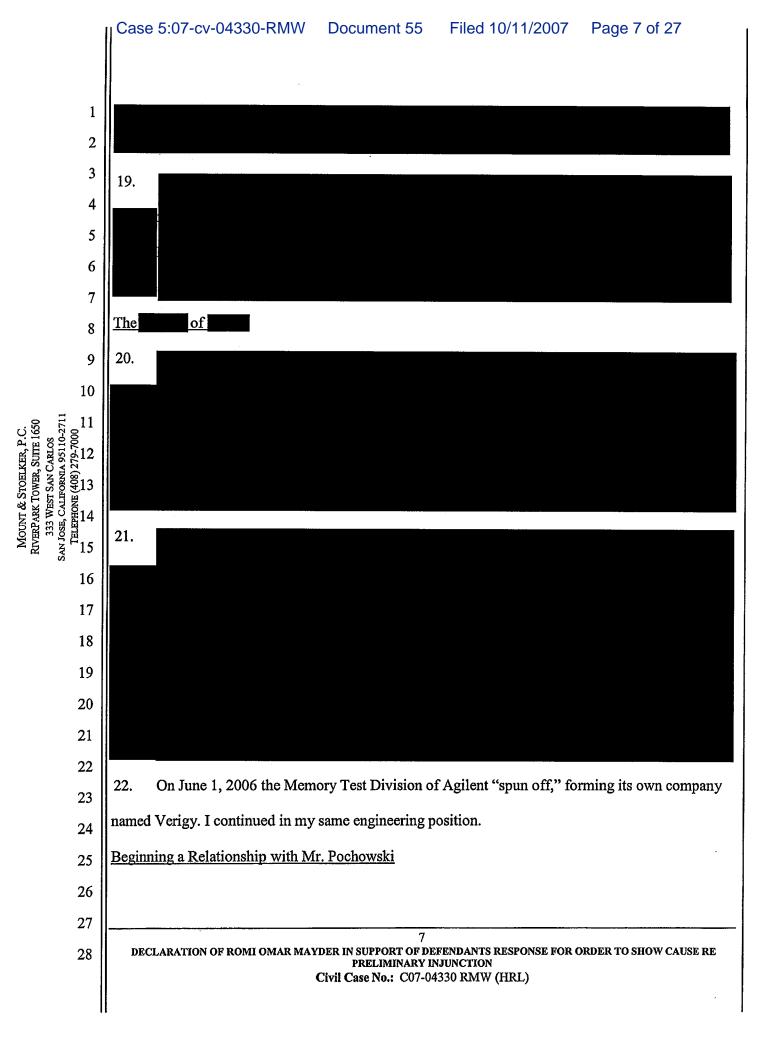
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23.	After notification of the	I contacted Bob Pochowski, the ex general
mana	ger of the Agilent Memory Test Division, to	o investigate what commercial opportunities might
exist i	for "probe card resource sharing" products.	Even after terminating from Agilent, I observed Mr.
Pocho	owski regularly meeting with Verigy manag	gement. He appeared to be a trusted advisor to the
remai	ning Agilent management team.	
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- 24. I was told by Edmundo DeLa Puente (Verigy's Master Design Engineer) that he and Mr. Pochowski regularly discussed technical research and development information, including the product roadmap. Mr. Pochowski informed me that he discussed Verigy business issues with Alan Hart while running at Ranch San Antonio at 11:30am every Thursday. Mr. Pochowski also informed me that had lunch with Gayn Erickson (the Verigy General Manager of Memory Test) regularly and they discussed the Verigy product roadmap. Due to these representations I trusted that Mr. Pochowski understood the status of Verigy's projects and that he remained loyal to Verigy.
- 26. I felt that there would be no competition with Verigy because these custom chips were

complementary, or adjacent, to Verigy's Memory chip tester business.

- I assumed they would also be willing to do so with any new business Mr. Pochowski and I formed.
- 27. In discussions with Bob Pochowski, he informed me that many memory chip manufacturers were already building some types of probe card resource sharing in house (San Disk, Samsung, Hynix), or hiring other companies (Formfactor, TouchDown Technologies, and TSE) to work with

them in developing custom probe card resource sharing products. We felt that this could be a business		
opportunity for us also.		
28.		
Pochowski my understanding was that the		
and that		
I believed it did not contain any Verigy trade secrets,		
and therefore did not mark it confidential.		
29. It appeared to me that others at Verigy did not consider much of the information I shared with		
Mr. Pochowski confidential, as all but one of the documents (the		
marked Confidential. I did not remove any confidentiality markings from documents before sending		
them to Mr. Pochowski, and believed that confidential documents were marked as such to ensure		
compliance with the standard CDA.		
(1) As shown in the declaration of Ken Hanh Duc Lai, Exhibit A, the		
is not marked Confidential.		
(2) As shown in the declaration of Ken Hanh Duc Lai, Exhibits B, C, and D, the		
are not marked Confidential.		
(3) As shown in the declarations of Ira Leventhal and Andrew Lee (exhibit A and		
exhibit B respectively to those declarations) the		
is not marked Confidential.		
30. Although in Verigy's complaint it shows a version of the		
marked Agilent Confidential, that very same document when viewed in the default mode of		

1	Microsoft Word does not show that marking. A true and correct copy of this view taken from the file
2	sent to
3	is shown in Exhibit D.
4	31. I did not believe the information I shared with Mr. Pochowski was Verigy Confidential
5	because information contained in those documents appear to all be available from public sources and
6	
7	generally known in the industry.
8	(1) The assume that (as shown in the declaration of Ken Hanh Duc Lai, Exhibit
9	A), identifies the These
10	specifications are generally obtainable from public datasheets, which specify the
11	pinout and electrical characteristics of the NAND flash memory.
12	(2) As shown in the declaration of Ken Hanh Duc Lai, Exhibits B, C, and D, the
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16	This information is shared by tester manufacturers with
17	every customer so that they can use that information to properly test their specific
18	DUTs. Customers are permitted to share this information with other vendors who
19	help complete the testing process, such as probe card manufacturers.
20	(3) As shown in the declarations of Ira Leventhal and Andrew Lee (exhibit A and
21	exhibit B respectively) the
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23	Specifications for SP4T switches can be easily
24	found on the web from multiple vendors, including Honeywell.
25	Good Faith Preparations for Leaving Verigy
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32.	On June 15, 2006 I registered the domain name "silicontests.com" with networksolutions.com
in pro	eparation to start my own business.
33.	After project, and in preparation for establishing STS,
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35.	On September 8, 2006 I filed a certificate of incorporation on behalf of Silicon Test Solutions,
LLC v	vith the Secretary of State of California, with myself as President. At the time of forming STS I
did no	t believe that I would compete with Verigy.
36.	At about this time I informed Verigy management that I had decided to leave Verigy to
pursue	other career opportunities. They requested that before leaving that I conduct a "knowledge
transfe	er" of information known to me that would be useful for Verigy to be successful in its future

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I worked long hours

my last two weeks at Verigy, despite having a newborn child at home.

37. On Wednesday, September 20, 2006 I conducted an exit interview with my manager Preet Paul Singh. At this time I returned all Verigy electronic devices to Mr. Singh. I also returned all Verigy confidential information that was known to me. I returned my security badge, as well, thus eliminating my ability to access anything in the building without specific Verigy authorization. I ceased doing any additional work related to my employment for Verigy at this time. My last day of salary payment was September 21, 2006. A true and correct copy of my last pay stub is attached as Exhibit A.

#### Post Verigy Efforts – A Complete Change of Target Customer

- 38. I never spoke with any potential customers for the STS Flash Enhancer product before terminating with Verigy. My first potential customer meeting was with who was introduced to me by Bob Pochowski. I did speak with potential suppliers such as (and to a lesser before leaving Verigy, regarding the feasibility of manufacturing an integrated circuit for a startup business, such as STS.
- Soon after terminating employment with Verigy, Alan Hart, a Verigy manager, asked if I 40. would consult with the company on writing intellectual property disclosures for Verigy patent applications. I agreed to help and was compensated for each disclosure that I completed. I was never asked to sign a Confidentiality or Non Disclosure Agreement during these consulting efforts. During this time Verigy sent me confidential information in order to complete the disclosures. I destroyed or

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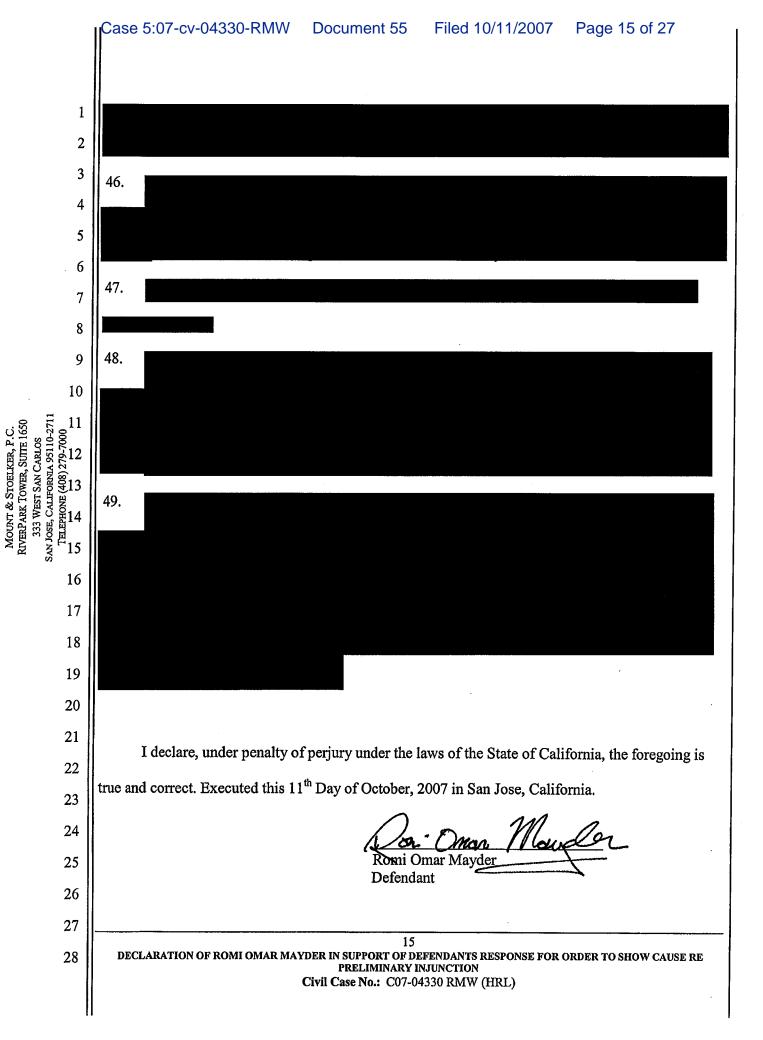
14.	To create a custom product for NOR flash memory manufacturers the chip would require a
ery so	ophisticated design and manufacture. One that I had never considered before. One that:
	(1) Would switch between read and write cycles must faster using only the Chip

(2) Would need to operate at much higher frequencies.

enable line of the DUTs.

- (3) Would need to support a much higher number of address, data, and control lines since NOR Memory is fully addressable.
- (4) Would allow the chip testers to automate control using only a single tester channel, with a pulse width modulation input ability.
- (5) Would generate very little heat due to wafer temperatures already at 150 degrees Celsius.
- (6) Would have less output capacitance, in the range of 20 micro farads, down from the original 50 micro farads contemplated for NAND flash memory.
- (7) Would require many more selectable switch configurations.
- (8) These changes were significant and





# EXHIBIT A

## EXHIBIT B

## EXHIBIT C

## EXHIBIT D

## EXHIBIT E

## EXHIBIT F